Advance Materials Development and Applied Mechanics

Edited by
Keishi Matsuda, P.S. Pa and Wiseroad Yun

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Advance Materials Development and Applied Mechanics

Selected, peer reviewed papers from the
3rd International Conference on
Advanced Materials Design and Mechanics
(ICAMDM2014),
May 23-24, 2014, Singapore

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Preface

Dear Distinguished Authors and Guests,

The Organizing Committee warmly welcomes you to 2014 the 3rd International Conference on Advanced Materials Design and Mechanics (ICAMDM2014) (TTP Conference ID: 1039), held on 23-24 May, 2014 in Singapore.

The aim of 3rd ICAMDM2014 is to present the latest research and results of scientists (professors, students, PhD Students, engineers, and post-doc scientist) related to Advanced Materials Design and Mechanics topics. This conference provides opportunities for the different areas delegates to exchange new ideas and application experiences face to face, to establish business or research relations and to find global partners for future collaboration.

After the peer-review process, the submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The selected papers and additional late-breaking contributions to be presented as lectures will make an exciting technical program. The conference program is extremely rich, featuring high-impact presentation. We hope that the conference results constituted significant contribution to the knowledge in these up to date scientific field.

The proceeding records the fully refereed papers presented at the conference. The main conference themes and tracks are Advanced Materials Design and Mechanics: Nanomaterials and Technologies, Advanced Material, Composite Materials and it's Applications and Technologies, Films, Coating and Surface Engineering and Other topics. Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process.

On behalf of the organizing committee, I would like to especially thank Dorthe, Sandra, Anne, Tanja and all the editors from Trans Tech Publications for their great support to 3rd ICAMDM2014. Without their excellent editorial work, 3rd ICAMDM2014 will not be published so timely and successfully.

Finally we wish all the authors and attendees of 3rd ICAMDM2014 a unique, rewarding and enjoyable memory at 3rd ICAMDM2014 in Singapore. We look forward to your participation in the 4th ICAMDM2015 in 2015.

With our warmest regards,

Keishi Matsuda, P. S. Pa, Wiseroad Yun
Conference Organizing Chair

June 10, 2014

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